

# DATA BOOK PACKAGE OUTLINE

LEADFRAME EXAMPLE
4222370

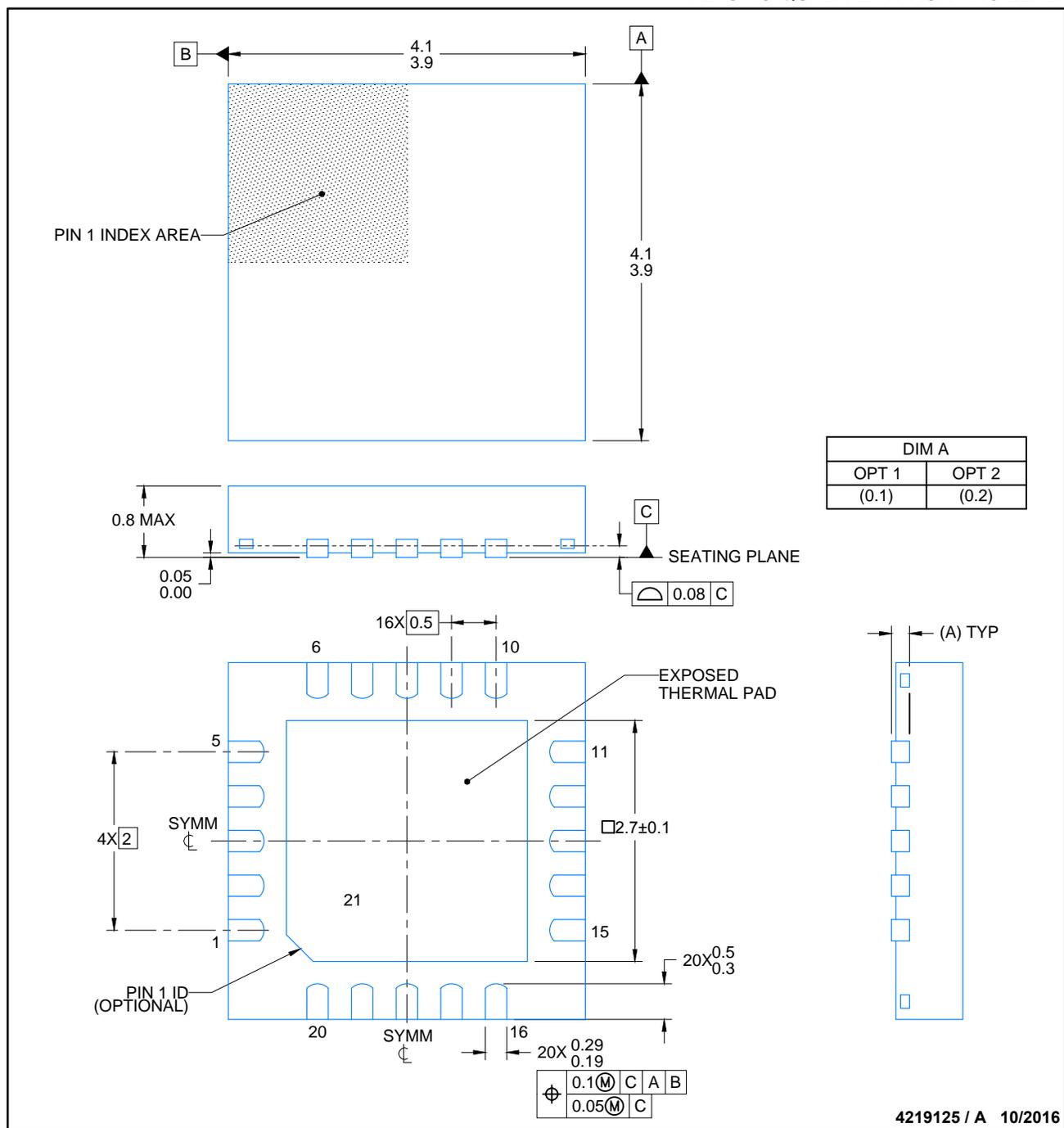
DRAFTSMAN: H. DENG	DATE: 09/12/2016		DIMENSIONS IN MILLIMETERS								
DESIGNER: H. DENG	DATE: 09/12/2016	 <b>TEXAS INSTRUMENTS</b> SEMICONDUCTOR OPERATIONS	CODE IDENTITY NUMBER 01295								
CHECKER: V. PAKU & T. LEQUANG	DATE: 09/12/2016		<b>ePOD, RTJ0020D / WQFN, 20 PIN, 0.5 MM PITCH</b>								
ENGINEER: T. TANG	DATE: 09/12/2016										
APPROVED: E. REY & D. CHIN	DATE: 10/06/2016										
RELEASED: WDM	DATE: 10/24/2016										
TEMPLATE INFO: EDGE# 4218519	DATE: 04/07/2016	<table border="1" style="display: inline-table; border-collapse: collapse;"> <tr> <td style="padding: 2px;">SCALE</td> <td style="padding: 2px;">SIZE</td> </tr> <tr> <td style="text-align: center;">15X</td> <td style="text-align: center;">A</td> </tr> </table>	SCALE	SIZE	15X	A	<table border="1" style="display: inline-table; border-collapse: collapse;"> <tr> <td style="padding: 2px;">REV</td> <td style="padding: 2px;">PAGE</td> </tr> <tr> <td style="text-align: center;">A</td> <td style="text-align: center;">1 OF 5</td> </tr> </table>	REV	PAGE	A	1 OF 5
SCALE	SIZE										
15X	A										
REV	PAGE										
A	1 OF 5										

# RTJ0020D

# PACKAGE OUTLINE

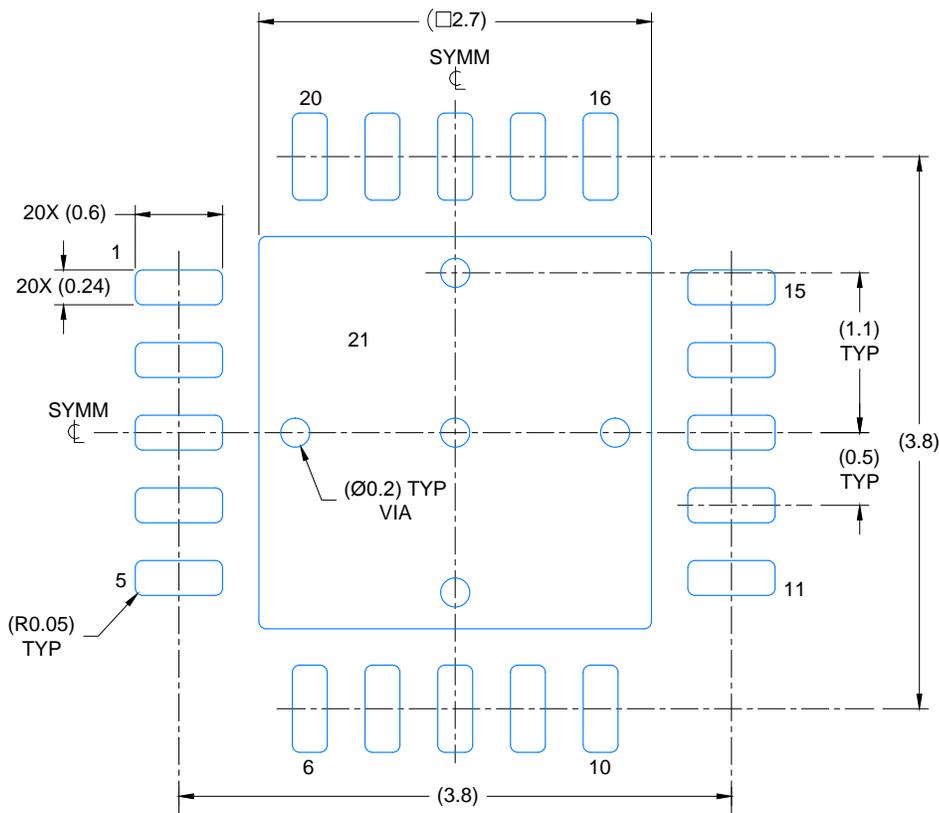
WQFN - 0.8 mm max height

PLASTIC QUAD FLATPACK - NO LEAD

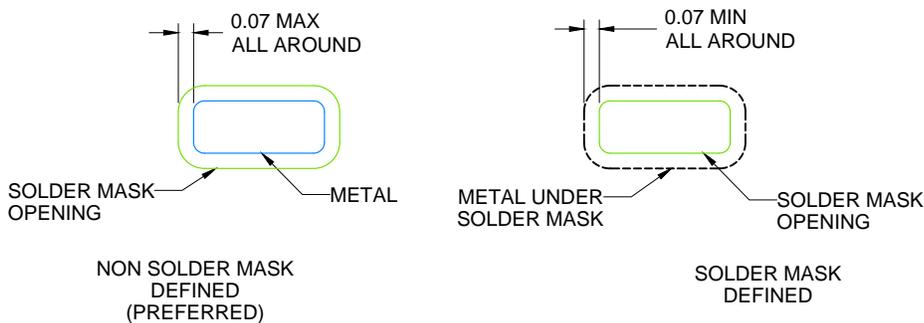


**NOTES:**

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.



LAND PATTERN EXAMPLE  
SCALE: 20X



SOLDER MASK DETAILS

4219125 / A 10/2016

NOTES: (continued)

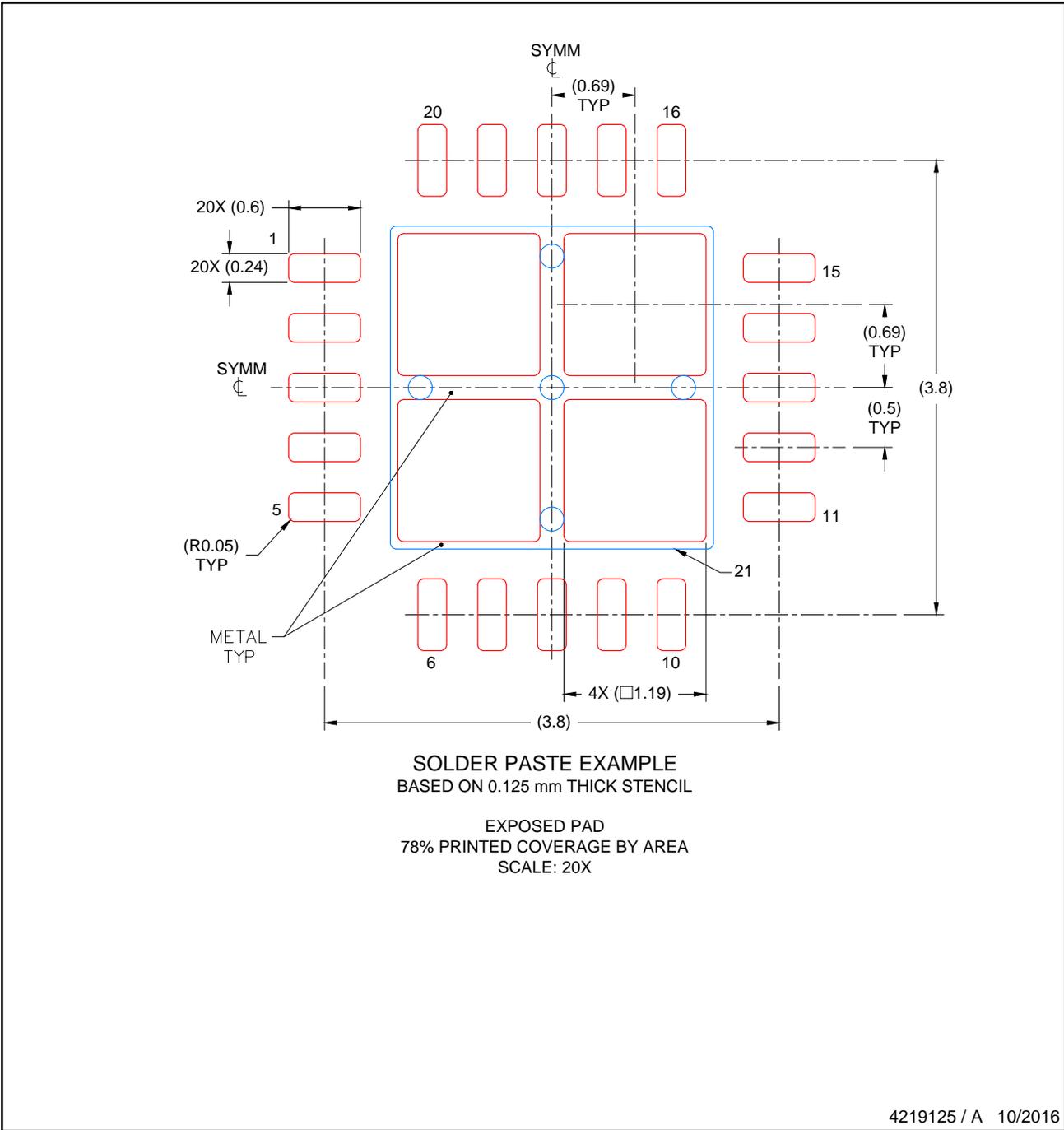
4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/slua271](http://www.ti.com/lit/slua271)).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

# EXAMPLE STENCIL DESIGN

WQFN - 0.8 mm max height

RTJ0020D

PLASTIC QUAD FLATPACK - NO LEAD



NOTES: (continued)

- 6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations..

# REVISIONS

REV	DESCRIPTION	ECR	DATE	ENGINEER / DRAFTSMAN
A	RELEASE NEW DRAWING	2160736	10/24/2016	T. TANG / H. DENG

SCALE	SIZE
NTS	A

4219125

REV	PAGE
A	5 OF 5

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